

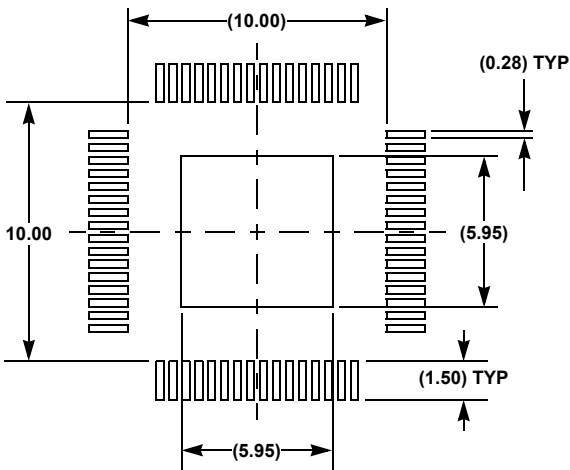
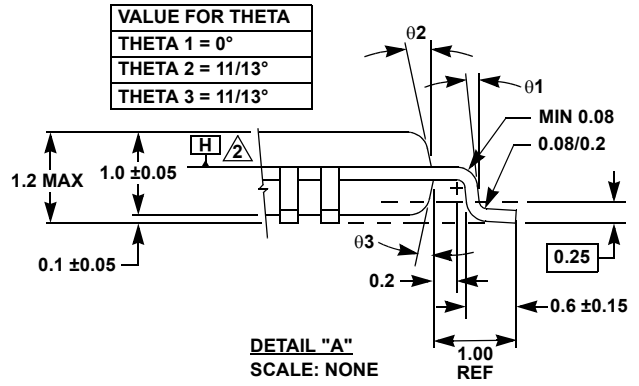
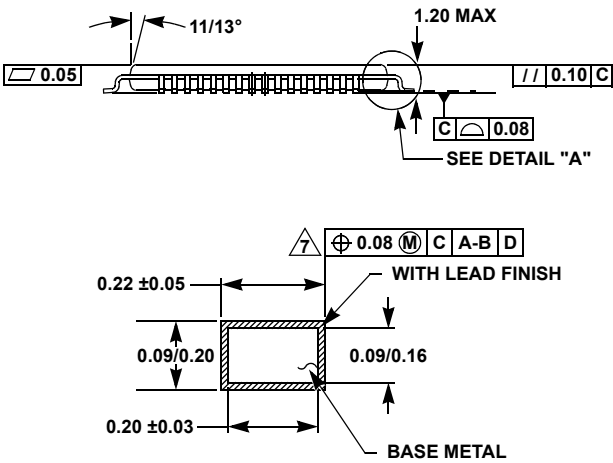
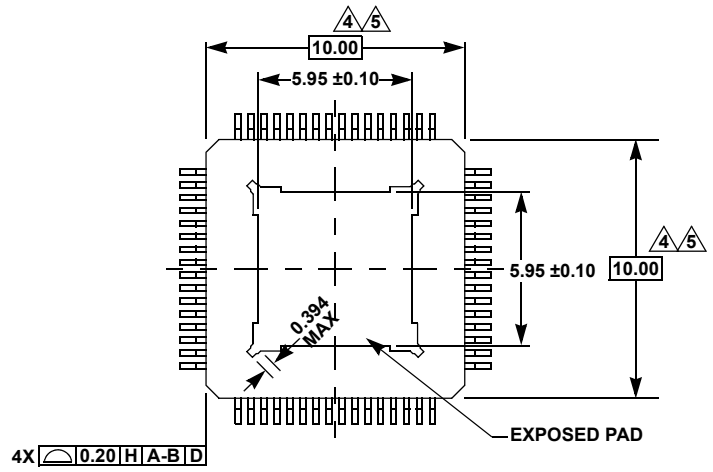
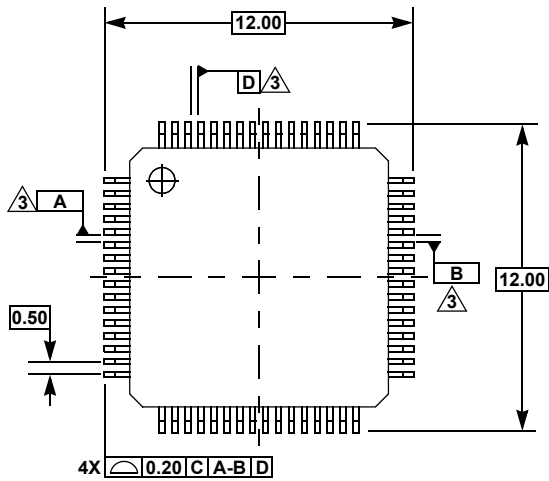
Plastic Packages for Integrated Circuits

Package Outline Drawing

Q64.10x10H

64 LEAD THIN PLASTIC QUAD FLATPACK PACKAGE WITH EXPOSED PAD (EP-TQFP)

Rev 0, 4/15



NOTES:

- All dimensioning and tolerancing conform to ANSI Y14.5-1982.
- Datum plane \square located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
- Datums \square - \square and \square to be determined at centerline between leads where leads exit plastic body at datum plane \square .
- Dimensions do not include mold protrusion. Allowable mold protrusion is 0.25mm. per side.
- These dimensions to be determined at datum plane \square .
- Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package.
- Dimension \square does not include dam bar protrusion. Allowable dam bar protrusion shall not cause the lead width to exceed the \square dimension by more than 0.08mm. Dam bar cannot be located on the lower radius of the foot. Minimum space between protrusion and an adjacent lead is 0.07mm.
 \triangle Exact shape of each corner is optional.
- Controlling dimension: millimeter.
- This outline conforms to JEDEC publication 95 registration MS-026, variation ACD.
- Dimensions in () are for reference only.